

# OPAx180 0.1 $\mu$ V/ $^{\circ}$ C 漂移、低噪声、轨至轨输出、36V 零漂移运算放大器

## 1 特性

- 低失调电压: 75 $\mu$ V (最大值)
- 零漂移: 0.1 $\mu$ V/ $^{\circ}$ C
- 低噪声: 10 nV/ $\sqrt{\text{Hz}}$
- 极低 1/f 噪声
- 出色的直流精度:
  - 电源抑制比 (PSRR): 126dB
  - 共模抑制比 (CMRR): 114dB
  - 开环路增益 (A<sub>OL</sub>): 120dB
- 静态电流: 525 $\mu$ A (最大值)
- 宽电源电压:  $\pm$ 2V 至  $\pm$ 18V
- 轨至轨输出:  
输入包括负电源轨
- 低偏置电流: 250pA (典型值)
- 已过滤射频干扰 (RFI) 的输入
- 微型尺寸封装

## 2 应用范围

- 桥式放大器
- 应力计
- 测试设备
- 传感器 应用
- 温度测量
- 电子称
- 医疗仪表
- 电阻式温度检测器
- 精密有源滤波器

## 3 说明

OPA180、OPA2180 和 OPA4180 运算放大器采用 TI 的专有零漂移技术，可同时提供低失调电压 (75 $\mu$ V)，并随时间推移和温度变化实现接近零漂移的性能。这些高精度、低静态电流微型运算放大器提供高输入阻抗和摆幅在电源轨 18mV 之内的轨至轨输出。输入共模范围包括负电源轨。电压范围为 4V 至 36V ( $\pm$ 2V 至  $\pm$ 18V) 的单电源或双电源均可使用。

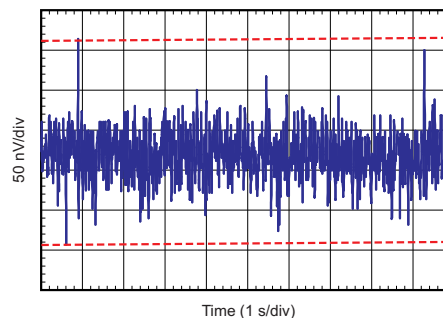
双通道版本 可采用 VSSOP-8 封装和 SOIC-8 封装。四通道版本可采用 SOIC-14 和 TSSOP-14 封装。单封装和四封装产品 (OPA180 和 OPA4180) 的额定温度范围为 -40 $^{\circ}$ C 至 +125 $^{\circ}$ C，双封装 (OPA2180) 的额定温度范围为 -40 $^{\circ}$ C 至 +105 $^{\circ}$ C。

器件信息<sup>(1)</sup>

器件名称	封装	封装尺寸 (标称值)
OPA180	SOT-23 (5)	1.60mm $\times$ 2.90mm
	VSSOP, 表面贴装小外形尺寸 (MSOP) (8)	3.00mm $\times$ 3.00mm
	SOIC (8)	4.90mm $\times$ 3.91mm
OPA2180	VSSOP, MSOP (8)	3.00mm $\times$ 3.00mm
	SOIC (8)	4.90mm $\times$ 3.91mm
OPA4180	TSSOP (14)	5.00mm $\times$ 4.40mm
	SOIC (14)	8.65mm $\times$ 3.91mm

(1) 如需了解所有可用封装，请参阅产品说明书末尾的可订购产品附录。

低噪声  
(峰值到峰值噪声 = 250nV)



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## 4 修订历史记录

注：之前版本的页码可能与当前版本有所不同。

Changes from Revision D (May 2014) to Revision E	Page
• 已更改在说明部分中将 OPA180 和 OPA4180 运行温度从“-40°C 至 +105°C”更改为“-40°C 至 +125°C” .....	1
• Added storage temperature parameter as the last row in the <i>Absolute Maximum Ratings</i> table .....	8
• Changed maximum operating temperature value from 105°C to 125°C in <i>Absolute Maximum Ratings</i> table .....	8
• Changed maximum operating temperature value from 105°C to 125°C in <i>Recommended Operating Conditions</i> table .....	8
• Changed input offset voltage drift temperature range from $T_A = -40^\circ\text{C to } 105^\circ\text{C}$ to $T_A = -40^\circ\text{C to } +125^\circ\text{C}$ in <i>Electrical Characteristics</i> table .....	10
• Changed power supply rejection ratio temperature range from $T_A = -40^\circ\text{C to } 105^\circ\text{C}$ to $T_A = -40^\circ\text{C to } +125^\circ\text{C}$ in <i>Electrical Characteristics</i> table .....	10
• Changed OPA180 input bias current temperature range from $T_A = -40^\circ\text{C to } 105^\circ\text{C}$ to $T_A = -40^\circ\text{C to } +125^\circ\text{C}$ in <i>Electrical Characteristics</i> table .....	10
• Added minimum OPA2180 input bias current value of 18 nA in <i>Electrical Characteristics</i> table .....	10
• Added minimum OPA180 input bias current value of 18 nA in <i>Electrical Characteristics</i> table .....	10
• Changed OPA180 input offset current temperature range from $T_A = -40^\circ\text{C to } 105^\circ\text{C}$ to $T_A = -40^\circ\text{C to } +125^\circ\text{C}$ in <i>Electrical Characteristics</i> table .....	10
• Added minimum OPA2180 input offset current value of 6 nA in <i>Electrical Characteristics</i> table .....	10
• Added minimum OPA180 input offset current value of 6 nA in <i>Electrical Characteristics</i> table .....	10
• Changed common-mode rejection ratio temperature range from $T_A = -40^\circ\text{C to } 105^\circ\text{C}$ to $T_A = -40^\circ\text{C to } +125^\circ\text{C}$ in <i>Electrical Characteristics</i> table .....	10
• Changed open-loop voltage gain temperature range from $T_A = -40^\circ\text{C to } 105^\circ\text{C}$ to $T_A = -40^\circ\text{C to } +125^\circ\text{C}$ in <i>Electrical Characteristics</i> table .....	10
• Changed voltage output swing from rail temperature range from $T_A = -40^\circ\text{C to } 105^\circ\text{C}$ to $T_A = -40^\circ\text{C to } +125^\circ\text{C}$ in <i>Electrical Characteristics</i> table .....	11
• Changed quiescent current temperature range from $T_A = -40^\circ\text{C to } 105^\circ\text{C}$ to $T_A = -40^\circ\text{C to } +125^\circ\text{C}$ in <i>Electrical Characteristics</i> table .....	11
• 已更改 operating temperature from "-40°C to +105°C" to "-40°C to +125°C" in <i>Feature Description</i> section .....	18
• Updated 图 34 .....	24
• 已更改 operating temperature from "-40°C to +105°C" to "-40°C to +125°C" in <i>Power Supply Recommendations</i>	

**修订历史记录 (接下页)**

section .....	<b>25</b>
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**Changes from Revision C (December 2012) to Revision D**
**Page**

• 已将格式更改为符合最新的产品说明书标准; 已添加器件功能模式, 应用范围和实施, 和 电源建议 章节, 并且已移动 现有章节 .....	1
• 将 OPA180 添加至文档 .....	1
• 已添加器件信息表 .....	1
• Deleted Package Information table .....	5
• OPA180 pinout drawings .....	5
• Added Pin Functions table .....	5
• Added Pin Functions table .....	6
• Added Pin Functions table .....	7
• Added Recommended Operating Conditions table .....	8
• Added Thermal Information: OPA180 table.....	9
• Changed Offset Voltage, <i>Long-term stability</i> parameter typical specification in Electrical Characteristics table.....	10
• Changed last sentence of <i>EMI Rejection</i> section.....	18

**Changes from Revision B (December 2011) to Revision C**
**Page**

• 已更改 将产品状态从混合状态更改为生产数据.....	1
• 已更改 将 OPA4180 状态更改为生产数据 .....	1
• Added package marking to OPA2180 VSSOP-8 row in Package Information table.....	5
• Deleted ordering number and transport media columns from Package Information table.....	5
• Changed Input Bias Current section in Electrical Characteristics ( $V_S = +4\text{ V to }+36\text{ V}$ ) table .....	10

**Changes from Revision A (November 2011) to Revision B**
**Page**

• Changed footnote 1 of Electrical Characteristics table.....	10
• Updated <a href="#">图 7</a> .....	13

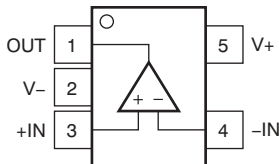
## 5 Device Comparison Table

**Table 1. Zero-Drift Amplifier Portfolio**

VERSION	PRODUCT	OFFSET VOLTAGE ( $\mu\text{V}$ )	OFFSET VOLTAGE DRIFT ( $\mu\text{V}/^\circ\text{C}$ )	BANDWIDTH (MHz)
Single	<a href="#">OPA188</a> (4 V to 36 V)	25	0.085	2
	<a href="#">OPA180</a> (4 V to 36 V)	75	0.35	2
	<a href="#">OPA333</a> (5 V)	10	0.05	0.35
	<a href="#">OPA378</a> (5 V)	50	0.25	0.9
	<a href="#">OPA735</a> (12 V)	5	0.05	1.6
Dual	<a href="#">OPA2188</a> (4 V to 36 V)	25	0.085	2
	<a href="#">OPA2180</a> (4 V to 36 V)	75	0.35	2
	<a href="#">OPA2333</a> (5 V)	10	0.05	0.35
	<a href="#">OPA2378</a> (5 V)	50	0.25	0.9
	<a href="#">OPA2735</a> (12 V)	5	0.05	1.6
Quad	<a href="#">OPA4188</a> (4 V to 36 V)	25	0.085	2
	<a href="#">OPA4180</a> (4 V to 36 V)	75	0.35	2
	<a href="#">OPA4330</a> (5 V)	50	0.25	0.35

## 6 Pin Configuration and Functions

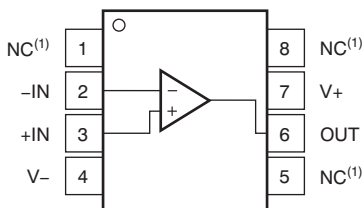
**OPA180 DBV Package  
5-Pin SOT-23  
(Top View)**



**Pin Functions**

PIN		I/O	DESCRIPTION
NAME	NO.		
-IN	4	I	Inverting input
+IN	3	I	Noninverting input
OUT	1	O	Output
V-	2	—	Negative supply or ground (for single-supply operation)
V+	5	—	Positive supply or ground (for single-supply operation)

**OPA180 D, DGK Packages  
8-Pin SO, MSOP  
Top View**

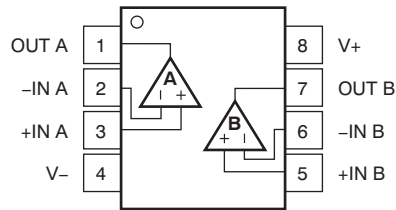


(1) NC- no internal connection

**Pin Functions: OPA180**

PIN		DESCRIPTION
NAME	NO.	
-IN	2	Inverting input
+IN	3	Noninverting input
NC	1, 5, 8	No connection
OUT	6	Output
V-	4	Negative power supply
V+	7	Positive power supply

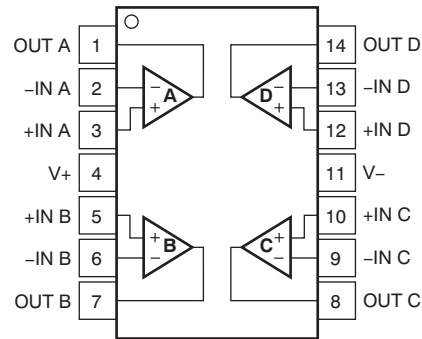
**OPA2180 D, DGK Packages**  
**8-Pin SOIC, VSSOP**  
**Top View**



**Pin Functions: OPA2180**

PIN		DESCRIPTION
NAME	NO.	
-IN A	2	Inverting input, channel A
+IN A	3	Noninverting input, channel A
-IN B	6	Inverting input, channel B
+IN B	5	Noninverting input, channel B
OUT A	1	Output, channel A
OUT B	7	Output, channel B
V-	4	Negative power supply
V+	8	Positive power supply

**OPA4180 D, PW Packages  
14-Pin SOIC, TSSOP  
(Top View)**



**Pin Functions: OPA4180**

PIN		DESCRIPTION
NAME	NO.	
-IN A	2	Inverting input, channel A
+IN A	3	Noninverting input, channel A
-IN B	6	Inverting input, channel B
+IN B	5	Noninverting input, channel B
-IN C	9	Inverting input, channel C
+IN C	10	Noninverting input, channel C
-IN D	13	Inverting input, channel D
+IN D	12	Noninverting input, channel D
OUT A	1	Output, channel A
OUT B	7	Output, channel B
OUT C	8	Output, channel C
OUT D	14	Output, channel D
V-	11	Negative supply or ground (for single-supply operation)
V+	4	Positive supply or ground (for single-supply operation)

## 7 Specifications

### 7.1 Absolute Maximum Ratings

 over operating free-air temperature range (unless otherwise noted)<sup>(1)</sup>

		MIN	MAX	UNIT
	Supply voltage		±20, ±40 (single-supply)	V
	Signal input terminals	Voltage	(V–) – 0.5      (V+) + 0.5	V
		Current	±10	mA
	Output short-circuit <sup>(2)</sup>	Continuous		
	Operating temperature	–55	125	°C
T <sub>J</sub>	Junction temperature		150	°C
T <sub>stg</sub>	Storage temperature	–65	150	°C

- (1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) Short-circuit to ground, one amplifier per package.

### 7.2 ESD Ratings

		MIN	MAX	UNIT
T <sub>stg</sub>	Storage temperature range	–65	150	°C
V <sub>(ESD)</sub>	Electrostatic discharge	Human body model (HBM), per ANSI/ESDA/JEDEC JS-001, all pins <sup>(1)</sup>	–1.5      1.5	kV
		Charged device model (CDM), per JEDEC specification JESD22-C101, all pins <sup>(2)</sup>	–1      1	

- (1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
- (2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

### 7.3 Recommended Operating Conditions

 over operating free-air temperature range (unless otherwise noted), R<sub>L</sub> = 10 kΩ connected to V<sub>S</sub> / 2, and V<sub>COM</sub> = V<sub>OUT</sub> = V<sub>S</sub> / 2, (unless otherwise noted)

		MIN	NOM	MAX	UNIT
Supply voltage [(V+) – (V–)]	Single-supply	4.5		36	V
	Bipolar-supply	±2.25		±18	V
Operating temperature		–40		125	°C



## 7.4 Thermal Information: OPA180

THERMAL METRIC <sup>(1)</sup>		OPA180			UNIT
		D (SOIC)	DBV (SOT-23)	DGK (MSOP)	
		8 PINS	5 PINS	8 PINS	
$R_{\theta JA}$	Junction-to-ambient thermal resistance	115.8	158.8	180.4	°C/W
$R_{\theta JC(top)}$	Junction-to-case(top) thermal resistance	60.1	60.7	67.9	°C/W
$R_{\theta JB}$	Junction-to-board thermal resistance	56.4	44.8	102.1	°C/W
$\Psi_{JT}$	Junction-to-top characterization parameter	12.8	1.6	10.4	°C/W
$\Psi_{JB}$	Junction-to-board characterization parameter	55.9	4.2	100.3	°C/W
$R_{\theta JC(bot)}$	Junction-to-case(bottom) thermal resistance	N/A	N/A	N/A	°C/W

- (1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC Package Thermal Metrics](#) application report.

## 7.5 Thermal Information: OPA2180

THERMAL METRIC <sup>(1)</sup>		OPA2180		UNIT
		D (SOIC)	DGK (MSOP)	
		8 PINS	8 PINS	
$R_{\theta JA}$	Junction-to-ambient thermal resistance	111	159.3	°C/W
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	54.9	37.4	°C/W
$R_{\theta JB}$	Junction-to-board thermal resistance	51.7	48.5	°C/W
$\Psi_{JT}$	Junction-to-top characterization parameter	9.3	1.2	°C/W
$\Psi_{JB}$	Junction-to-board characterization parameter	51.1	77.1	°C/W
$R_{\theta JC(bot)}$	Junction-to-case (bottom) thermal resistance	N/A	N/A	°C/W

- (1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC Package Thermal Metrics](#) application report.

## 7.6 Thermal Information: OPA4180

THERMAL METRIC <sup>(1)</sup>		OPA4180		UNIT
		D (SOIC)	PW (TSSOP)	
		14 PINS	14 PINS	
$R_{\theta JA}$	Junction-to-ambient thermal resistance	93.2	106.9	°C/W
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	51.8	24.4	°C/W
$R_{\theta JB}$	Junction-to-board thermal resistance	49.4	59.3	°C/W
$\Psi_{JT}$	Junction-to-top characterization parameter	13.5	0.6	°C/W
$\Psi_{JB}$	Junction-to-board characterization parameter	42.2	54.3	°C/W
$R_{\theta JC(bot)}$	Junction-to-case (bottom) thermal resistance	N/A	N/A	°C/W

- (1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC Package Thermal Metrics](#) application report.

## 7.7 Electrical Characteristics: $V_S = \pm 2\text{ V to } \pm 18\text{ V}$ ( $V_S = 4\text{ V to } 36\text{ V}$ )

 at  $T_A = 25^\circ\text{C}$ ,  $R_L = 10\text{ k}\Omega$  connected to  $V_S / 2$ , and  $V_{\text{COM}} = V_{\text{OUT}} = V_S / 2$ , unless otherwise noted.

PARAMETER		CONDITIONS	MIN	TYP	MAX	UNIT
<b>OFFSET VOLTAGE</b>						
$V_{\text{IO}}$	Input offset voltage			15	75	$\mu\text{V}$
$dV_{\text{IO}}/dT$	Input offset voltage drift	$T_A = -40^\circ\text{C to } +125^\circ\text{C}$		0.1	0.35	$\mu\text{V}/^\circ\text{C}$
PSRR	Power supply rejection ratio	$V_S = 4\text{ V to } 36\text{ V}$ , $V_{\text{CM}} = V_S / 2$		0.1	0.5	$\mu\text{V}/\text{V}$
		$T_A = -40^\circ\text{C to } +125^\circ\text{C}$ , $V_S = 4\text{ V to } 36\text{ V}$ , $V_{\text{CM}} = V_S / 2$			0.5	$\mu\text{V}/\text{V}$
	Long-term stability			4 <sup>(1)</sup>		$\mu\text{V}$
	Channel separation, DC			1		$\mu\text{V}/\text{V}$
<b>INPUT BIAS CURRENT</b>						
$I_{\text{IB}}$	Input bias current	OPA2180		$\pm 0.25$	$\pm 1$	nA
		OPA2180: $T_A = -40^\circ\text{C to } +105^\circ\text{C}$	18		$\pm 5$	nA
		OPA180, OPA4180		$\pm 0.25$	$\pm 1.7$	nA
		OPA180, OPA4180: $T_A = -40^\circ\text{C to } +125^\circ\text{C}$	18		$\pm 6$	nA
$I_{\text{IO}}$	Input offset current	OPA2180		$\pm 0.5$	$\pm 2$	nA
		OPA2180: $T_A = -40^\circ\text{C to } +105^\circ\text{C}$	6		$\pm 2.5$	nA
		OPA180, OPA4180			$\pm 3.4$	nA
		OPA180, OPA4180: $T_A = -40^\circ\text{C to } +125^\circ\text{C}$	6		$\pm 3$	nA
<b>NOISE</b>						
	Input voltage noise	$f = 0.1\text{ Hz to } 10\text{ Hz}$		0.25		$\mu\text{V}_{\text{PP}}$
$e_n$	Input voltage noise density	$f = 1\text{ kHz}$		10		$\text{nV}/\sqrt{\text{Hz}}$
$i_n$	Input current noise density	$f = 1\text{ kHz}$		10		$\text{fA}/\sqrt{\text{Hz}}$
<b>INPUT VOLTAGE RANGE</b>						
$V_{\text{CM}}$	Common-mode voltage range		$V^-$		$(V^+) - 1.5$	V
CMRR	Common-mode rejection ratio	$(V^-) < V_{\text{CM}} < (V^+) - 1.5\text{ V}$	104	114		dB
		$T_A = -40^\circ\text{C to } +125^\circ\text{C}$ , $(V^-) + 0.5\text{ V} < V_{\text{CM}} < (V^+) - 1.5\text{ V}$	100	104		dB
<b>INPUT IMPEDANCE</b>						
$Z_{\text{id}}$	Differential			100    6		$\text{M}\Omega \parallel \text{pF}$
$Z_{\text{ic}}$	Common-mode			6    9.5		$10^{12}\ \Omega \parallel \text{pF}$
<b>OPEN-LOOP GAIN</b>						
$A_{\text{OL}}$	Open-loop voltage gain	$(V^-) + 500\text{ mV} < V_{\text{O}} < (V^+) - 500\text{ mV}$ $R_L = 10\text{ k}\Omega$	110	120		dB
		$T_A = -40^\circ\text{C to } +125^\circ\text{C}$ $(V^-) + 500\text{ mV} < V_{\text{O}} < (V^+) - 500\text{ mV}$ , $R_L = 10\text{ k}\Omega$	104	114		dB
<b>FREQUENCY RESPONSE</b>						
GBW	Gain bandwidth product			2		MHz
SR	Slew rate	$G = 1$		0.8		$\text{V}/\mu\text{s}$
$t_s$	Settling time	0.1%	$V_S = \pm 18\text{ V}$ , $G = 1$ , 10-V step	22		$\mu\text{s}$
		0.01%	$V_S = \pm 18\text{ V}$ , $G = 1$ , 10-V step	30		$\mu\text{s}$
$t_{\text{or}}$	Overload recovery time	$V_{\text{IN}} \times G = V_S$		1		$\mu\text{s}$
THD+N	Total harmonic distortion + noise	$f = 1\text{ kHz}$ , $G = 1$ , $V_{\text{OUT}} = 1\text{ V}_{\text{RMS}}$		0.0001%		

 (1) 1000-hour life test at  $125^\circ\text{C}$  demonstrated randomly distributed variation in the range of measurement limits, or approximately  $4\ \mu\text{V}$ .

**Electrical Characteristics:  $V_S = \pm 2\text{ V}$  to  $\pm 18\text{ V}$  ( $V_S = 4\text{ V}$  to  $36\text{ V}$ ) (continued)**

 at  $T_A = 25^\circ\text{C}$ ,  $R_L = 10\text{ k}\Omega$  connected to  $V_S / 2$ , and  $V_{\text{COM}} = V_{\text{OUT}} = V_S / 2$ , unless otherwise noted.

PARAMETER	CONDITIONS	MIN	TYP	MAX	UNIT
<b>OUTPUT</b>					
Voltage output swing from rail	No load		8	18	mV
	$R_L = 10\text{ k}\Omega$		250	300	mV
	$T_A = -40^\circ\text{C}$ to $+125^\circ\text{C}$ $R_L = 10\text{ k}\Omega$		325	360	mV
$I_{\text{OS}}$	Short-circuit current		$\pm 18$		mA
$r_o$	Output resistance (open loop)	$f = 2\text{ MHz}$ , $I_O = 0\text{ mA}$		120	$\Omega$
$C_{\text{LOAD}}$	Capacitive load drive		1		nF
<b>POWER SUPPLY</b>					
$V_S$	Operating voltage range	$\pm 2$ (or 4)		$\pm 18$ (or 36)	V
$I_Q$	Quiescent current (per amplifier)			450	$\mu\text{A}$
		$T_A = -40^\circ\text{C}$ to $+125^\circ\text{C}$ $I_O = 0\text{ mA}$		600	$\mu\text{A}$
<b>TEMPERATURE</b>					
	Specified range		-40	105	$^\circ\text{C}$
	Operating range		-40	105	$^\circ\text{C}$

## 7.8 Typical Characteristics: Table of Graphs

**表 2. Characteristic Performance Measurements**

DESCRIPTION	FIGURE
$I_B$ and $I_{OS}$ vs Common-Mode Voltage	图 1
Input Bias Current vs Temperature	图 2
Output Voltage Swing vs Output Current (Maximum Supply)	图 3
CMRR vs Temperature	图 4
0.1-Hz to 10-Hz Noise	图 5
Input Voltage Noise Spectral Density vs Frequency	图 6
Open-Loop Gain and Phase vs Frequency	图 7
Open-Loop Gain vs Temperature	图 8
Open-Loop Output Impedance vs Frequency	图 9
Small-Signal Overshoot vs Capacitive Load (100-mV Output Step)	图 10, 图 11
No Phase Reversal	图 12
Positive Overload Recovery	图 13
Negative Overload Recovery	图 14
Small-Signal Step Response (100 mV)	图 15, 图 16
Large-Signal Step Response	图 17, 图 18
Large-Signal Settling Time (10-V Positive Step)	图 19
Large-Signal Settling Time (10-V Negative Step)	图 20
Short-Circuit Current vs Temperature	图 21
Maximum Output Voltage vs Frequency	图 22
Channel Separation vs Frequency	图 23
EMIRR IN+ vs Frequency	图 24

### 7.9 Typical Characteristics

$V_S = \pm 18\text{ V}$ ,  $V_{CM} = V_S / 2$ ,  $R_{LOAD} = 10\text{ k}\Omega$  connected to  $V_S / 2$ , and  $C_L = 100\text{ pF}$ , unless otherwise noted.

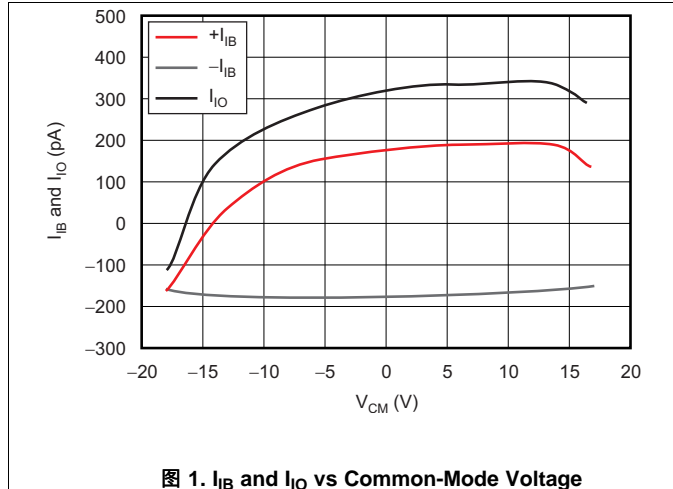


图 1.  $I_{IB}$  and  $I_{IO}$  vs Common-Mode Voltage

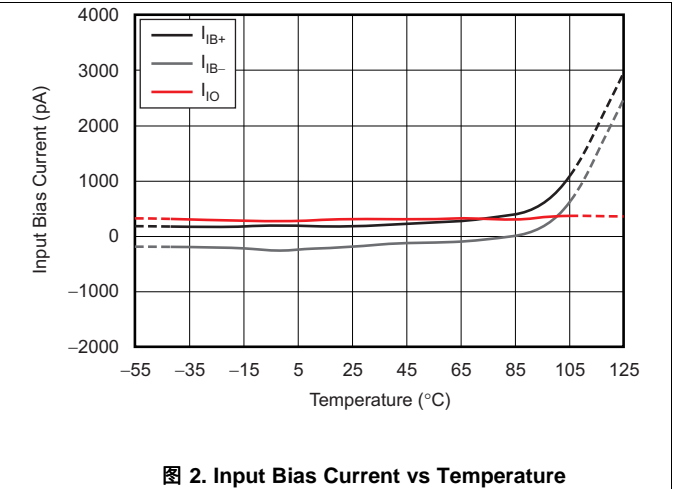


图 2. Input Bias Current vs Temperature

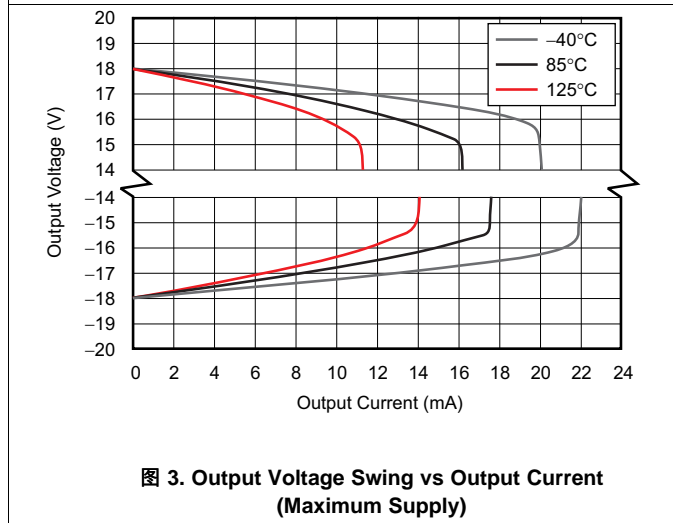
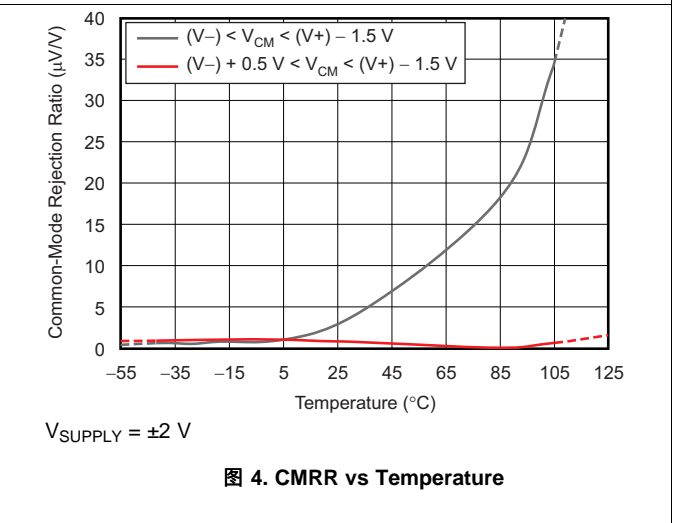


图 3. Output Voltage Swing vs Output Current (Maximum Supply)



$V_{SUPPLY} = \pm 2\text{ V}$

图 4. CMRR vs Temperature

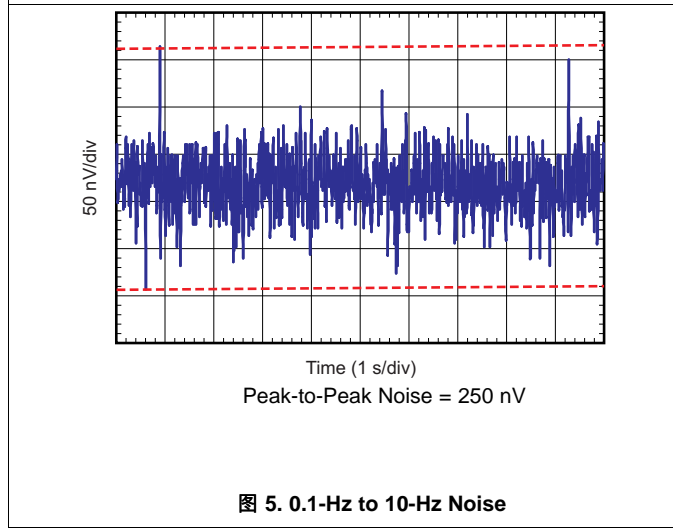


图 5. 0.1-Hz to 10-Hz Noise

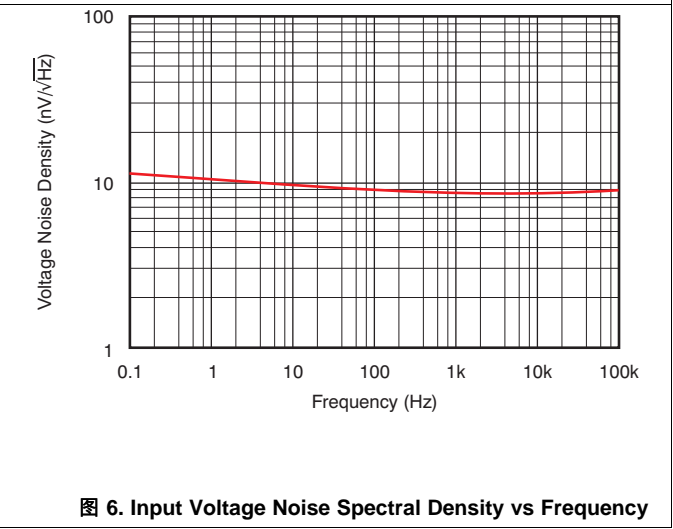


图 6. Input Voltage Noise Spectral Density vs Frequency

Typical Characteristics (接下页)

$V_S = \pm 18\text{ V}$ ,  $V_{CM} = V_S / 2$ ,  $R_{LOAD} = 10\text{ k}\Omega$  connected to  $V_S / 2$ , and  $C_L = 100\text{ pF}$ , unless otherwise noted.

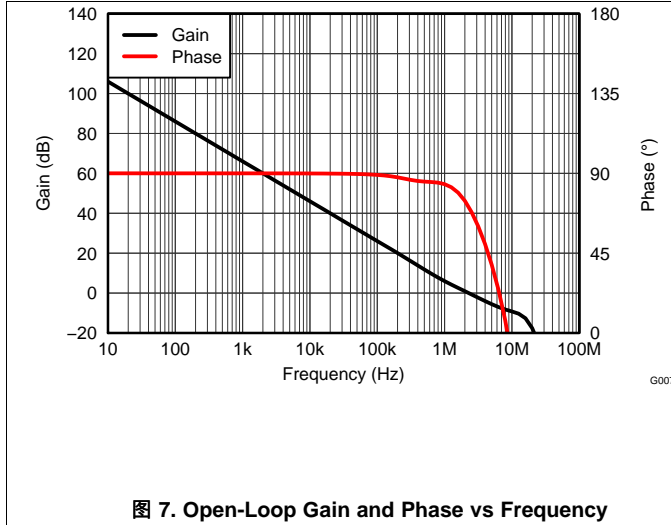


图 7. Open-Loop Gain and Phase vs Frequency

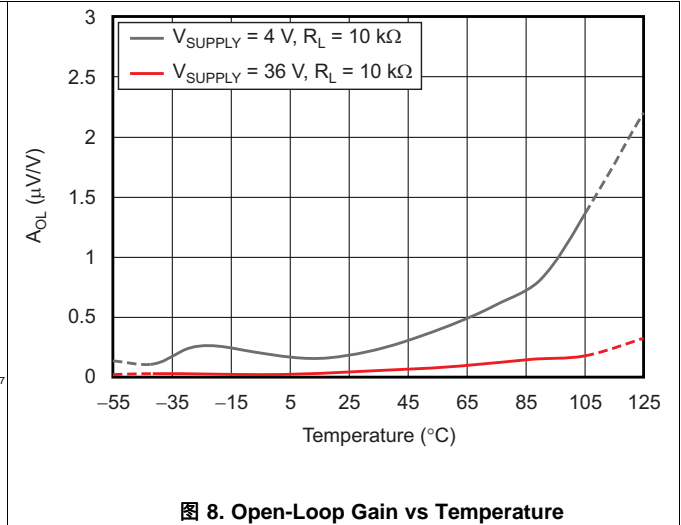


图 8. Open-Loop Gain vs Temperature

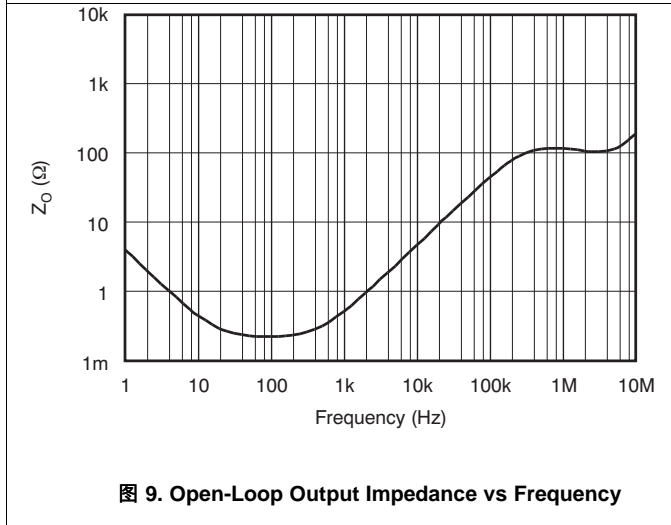


图 9. Open-Loop Output Impedance vs Frequency

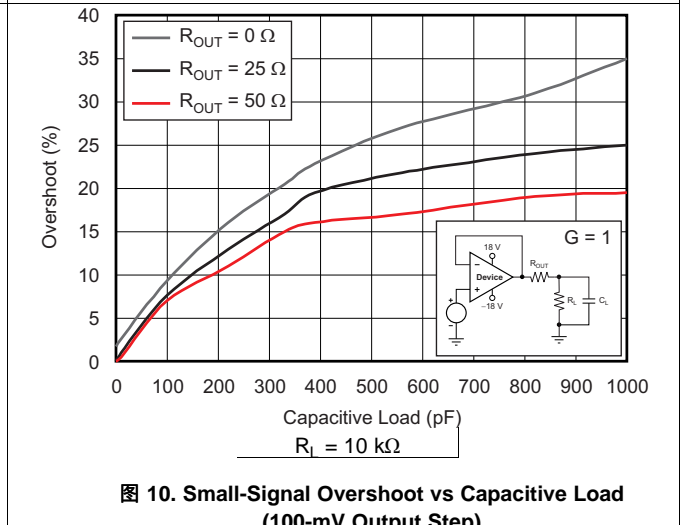


图 10. Small-Signal Overshoot vs Capacitive Load (100-mV Output Step)

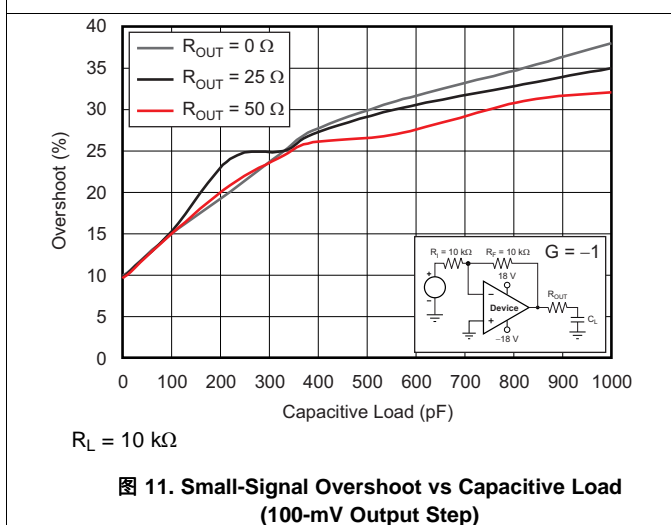


图 11. Small-Signal Overshoot vs Capacitive Load (100-mV Output Step)

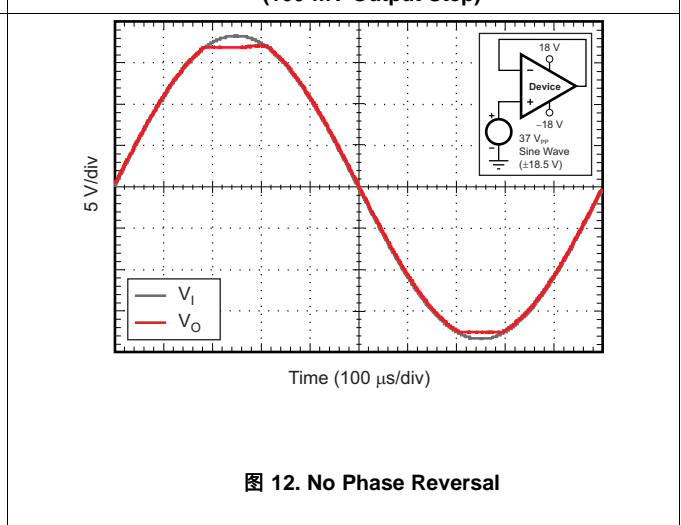


图 12. No Phase Reversal

Typical Characteristics (接下页)

$V_S = \pm 18\text{ V}$ ,  $V_{CM} = V_S / 2$ ,  $R_{LOAD} = 10\text{ k}\Omega$  connected to  $V_S / 2$ , and  $C_L = 100\text{ pF}$ , unless otherwise noted.

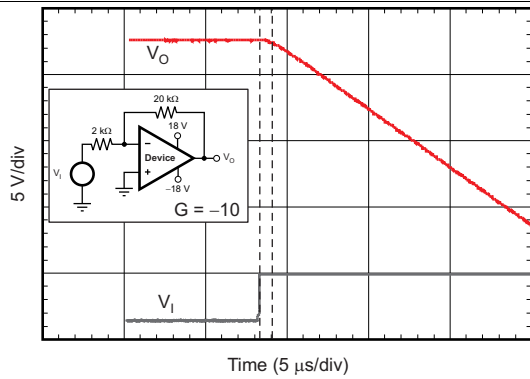


图 13. Positive Overload Recovery

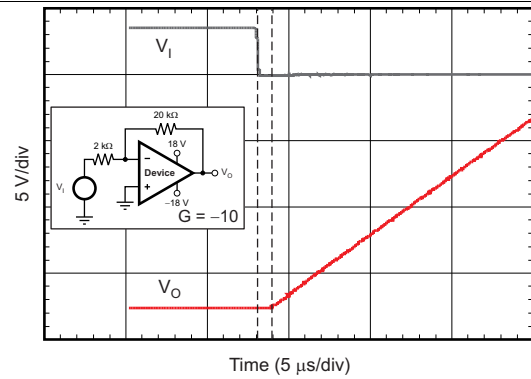


图 14. Negative Overload Recovery

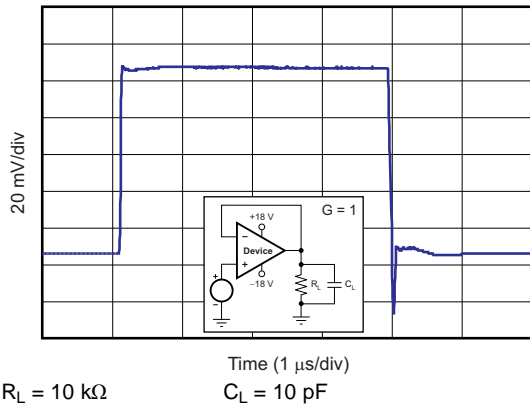


图 15. Small-Signal Step Response (100 mV)

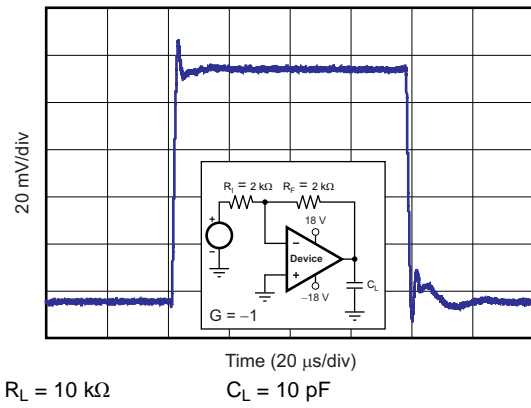


图 16. Small-Signal Step Response (100 mV)

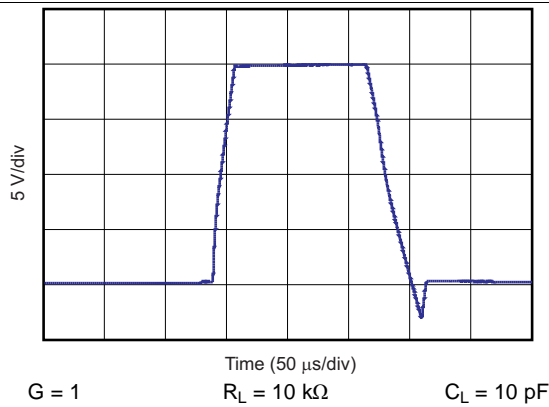


图 17. Large-Signal Step Response

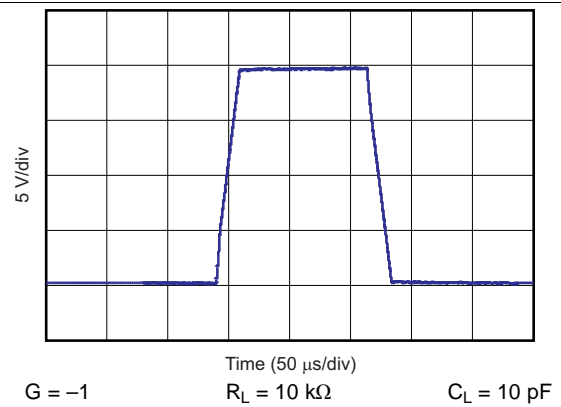
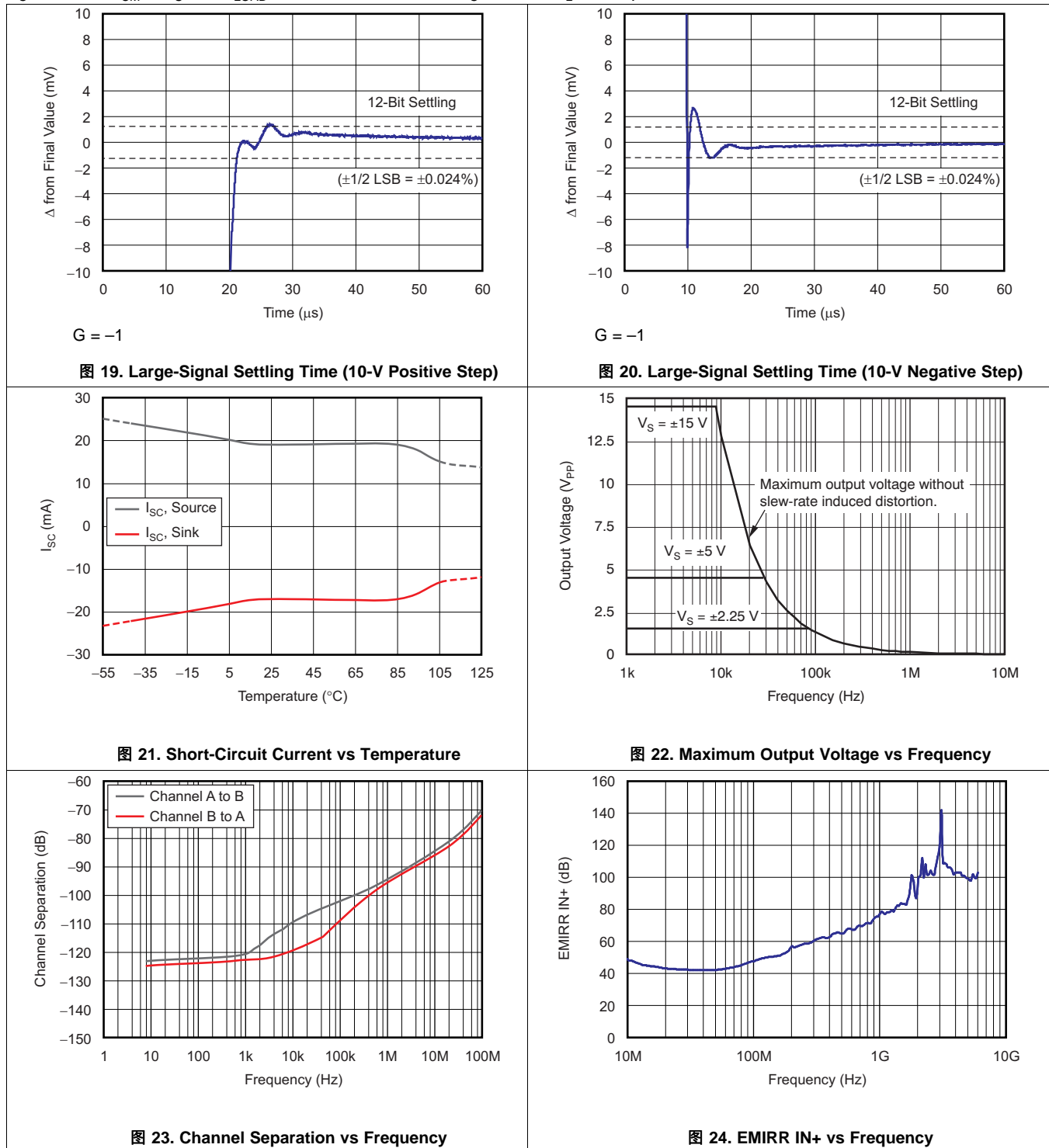


图 18. Large-Signal Step Response

Typical Characteristics (接下页)

$V_S = \pm 18\text{ V}$ ,  $V_{CM} = V_S / 2$ ,  $R_{LOAD} = 10\text{ k}\Omega$  connected to  $V_S / 2$ , and  $C_L = 100\text{ pF}$ , unless otherwise noted.



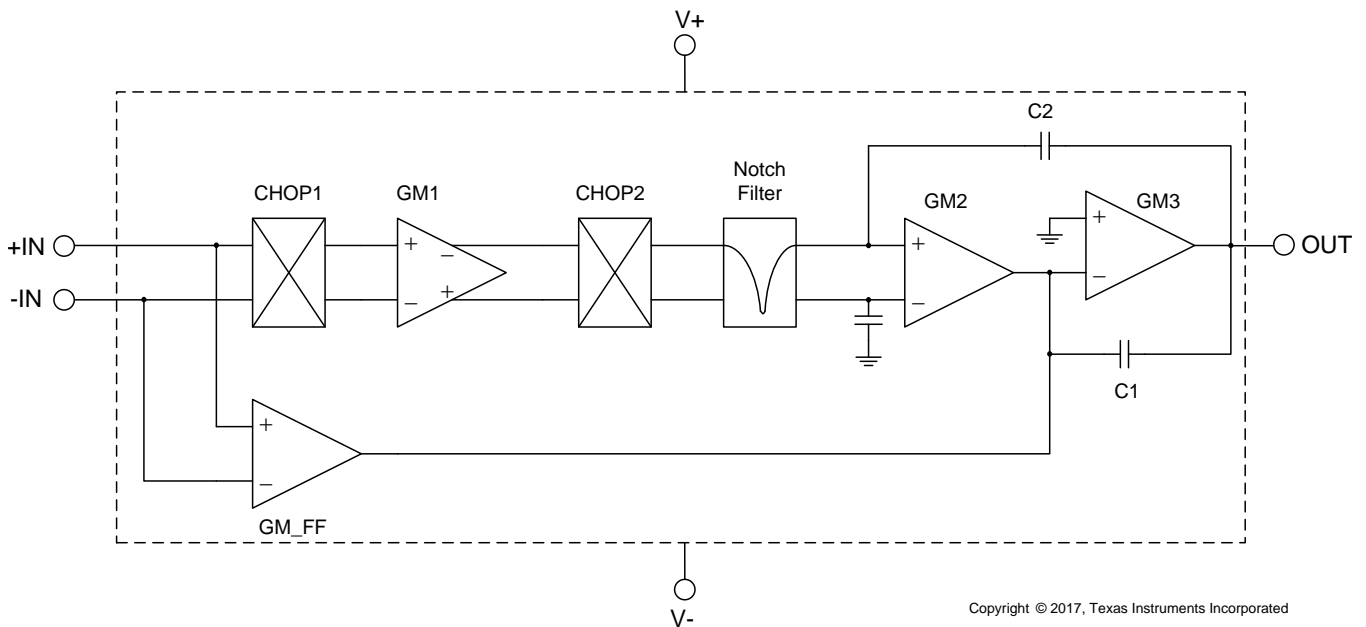


## 8 Detailed Description

### 8.1 Overview

The OPAx180 family of operational amplifiers combine precision offset and drift with excellent overall performance, making them designed for many precision applications. The precision offset drift of only  $0.1 \mu\text{V}/^\circ\text{C}$  provides stability over the entire temperature range. In addition, the devices offer excellent overall performance with high CMRR, PSRR, and  $A_{OL}$ . As with all amplifiers, applications with noisy or high-impedance power supplies require decoupling capacitors close to the device pins. In most cases,  $0.1\text{-}\mu\text{F}$  capacitors are adequate.

### 8.2 Functional Block Diagram



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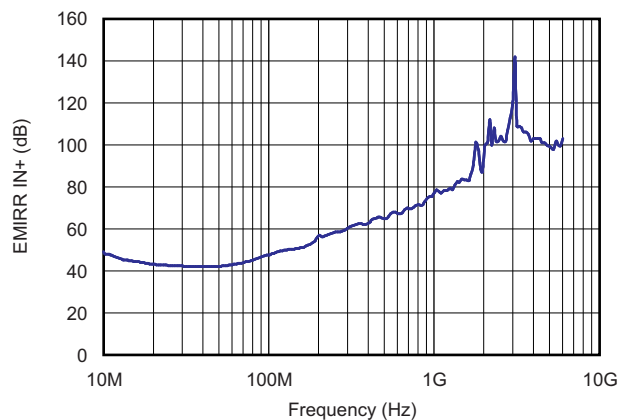
## 8.3 Feature Description

### 8.3.1 Operating Characteristics

The OPAx180 family of amplifiers is specified for operation from 4 V to 36 V ( $\pm 2$  V to  $\pm 18$  V). Many of the specifications apply from  $-40^{\circ}\text{C}$  to  $+125^{\circ}\text{C}$ . Parameters that can exhibit significant variance with regard to operating voltage or temperature are presented in the [Typical Characteristics](#).

### 8.3.2 EMI Rejection

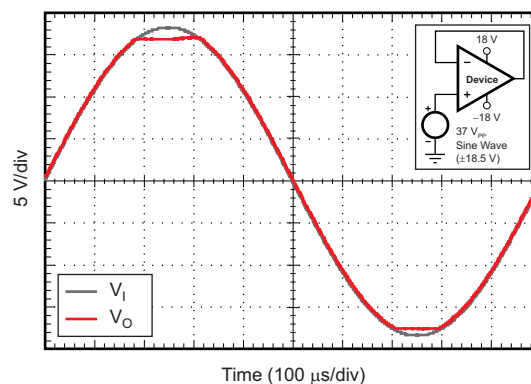
The OPAx180 family uses integrated electromagnetic interference (EMI) filtering to reduce the effects of EMI interference from sources such as wireless communications and densely populated boards with a mix of analog signal chain and digital components. EMI immunity can improve with circuit design techniques; the OPAx180 family benefits from these design improvements. Texas Instruments has developed the ability to accurately measure and quantify the immunity of an operational amplifier over a broad frequency spectrum extending from 10 MHz to 6 GHz. [Figure 25](#) shows the results of this testing on the OPAx180 family. For more detailed information, see the [EMI Rejection Ratio of Operational Amplifiers](#) application report, available for download from [www.ti.com](http://www.ti.com).



**图 25. OPAx180 EMIRR Testing**

### 8.3.3 Phase-Reversal Protection

The OPAx180 family has an internal phase-reversal protection. Many op amps exhibit a phase reversal when the input is driven beyond the linear common-mode range. This condition is most often encountered in noninverting circuits when the input is driven beyond the specified common-mode voltage range, causing the output to reverse into the opposite rail. The input of the OPAx180 prevents phase reversal with excessive common-mode voltage. Instead, the output limits into the appropriate rail. This performance is shown in [Figure 26](#).

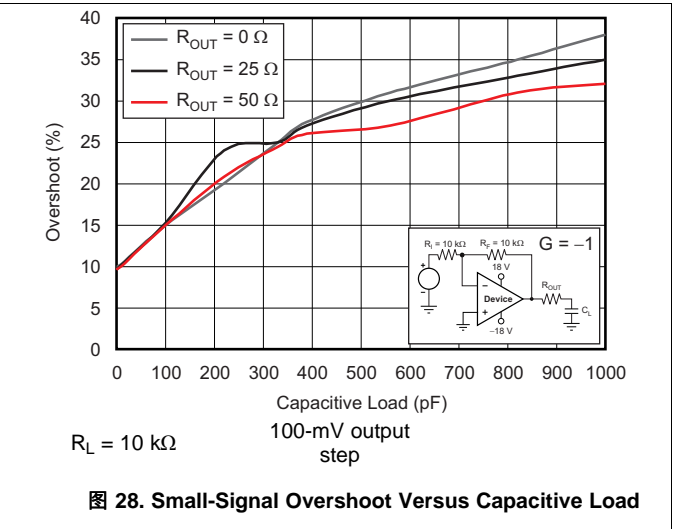
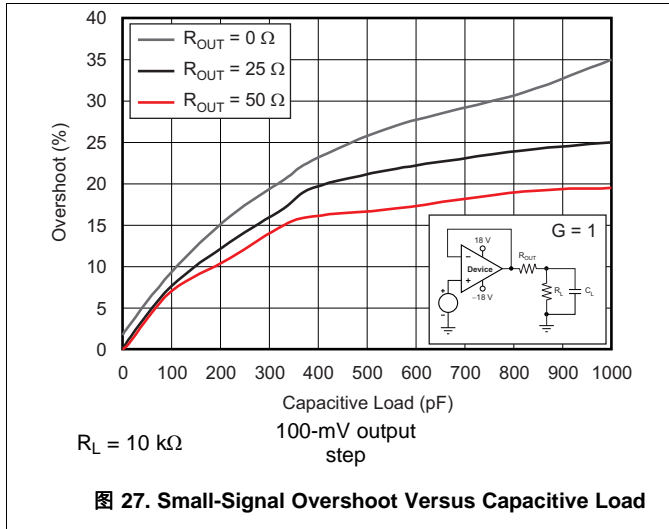


**图 26. No Phase Reversal**

Feature Description (接下页)

8.3.4 Capacitive Load and Stability

The dynamic characteristics of the OPAx180 are optimized for a range of common operating conditions. The combination of low closed-loop gain and high capacitive loads decreases the phase margin of the amplifier and can lead to gain peaking or oscillations. As a result, heavier capacitive loads must be isolated from the output. The simplest way to achieve this isolation is to add a small resistor (for example,  $R_{OUT}$  equal to  $50\ \Omega$ ) in series with the output. 图 27 和 图 28 illustrate graphs of small-signal overshoot versus capacitive load for several values of  $R_{OUT}$ . See the *Feedback Plots Define Op Amp AC Performance*, application report, available for download from the TI website, for details of analysis techniques and application circuits.



8.3.5 Electrical Overstress

Designers often ask questions about the capability of an operational amplifier to withstand electrical overstress. These questions tend to focus on the device inputs, but may involve the supply voltage pins or even the output pin. Each of these different pin functions have electrical stress limits determined by the voltage breakdown characteristics of the particular semiconductor fabrication process and specific circuits connected to the pin. Additionally, internal electrostatic discharge (ESD) protection is built into these circuits to protect them from accidental ESD events both before and during product assembly.

These ESD protection diodes also provide in-circuit, input overdrive protection, as long as the current is limited to 10 mA as stated in the *Absolute Maximum Ratings* table. 图 29 shows how a series input resistor may be added to the driven input to limit the input current. The added resistor contributes thermal noise at the amplifier input and the value must be kept to a minimum in noise-sensitive applications.

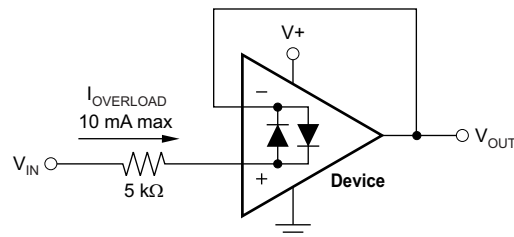


图 29. Input Current Protection

An ESD event produces a short duration, high-voltage pulse that is transformed into a short duration, high-current pulse as the pulse discharges through a semiconductor device. The ESD protection circuits are designed to provide a current path around the operational amplifier core to protect the core from damage. The energy absorbed by the protection circuitry is then dissipated as heat.

## Feature Description (接下页)

When the operational amplifier connects into a circuit, the ESD protection components are intended to remain inactive and not become involved in the application circuit operation. However, circumstances may arise when an applied voltage exceeds the operating voltage range of a given pin. If this condition occurs, there is a risk that some of the internal ESD protection circuits may be biased on, and conduct current. Any such current flow occurs through ESD cells and rarely involves the absorption device.

If there is an uncertainty about the ability of the supply to absorb this current, external zener diodes may be added to the supply pins. The zener voltage must be selected so the diode does not turn on during normal operation.

However, the zener voltage must be low enough so that the zener diode conducts if the supply pin begins to rise above the safe operating supply voltage level.

### 8.4 Device Functional Modes

The OPAx180, OPA2180, and OPA4180 devices are powered on when the supply is connected. These devices can operate as a single-supply operational amplifier or dual-supply amplifier depending on the application. In single-supply operation with  $V_-$  at ground (0 V),  $V_+$  can be any value between 4 V and 36 V. In dual-supply operation, the supply voltage difference between  $V_-$  and  $V_+$  is from 4 V to 36 V. Typical examples of dual-supply configuration are  $\pm 5$  V,  $\pm 10$  V,  $\pm 15$  V, and  $\pm 18$  V. However, the supplies must not be symmetrical. Less common examples are  $V_-$  at  $-3$  V and  $V_+$  at 9 V, or  $V_-$  at  $-16$  V and  $V_+$  at 5 V. Any combination where the difference between  $V_-$  and  $V_+$  is at least 4 V and no greater than 36 V is within the normal operating capabilities of these devices.

## 9 Application and Implementation

### 9.1 Application Information

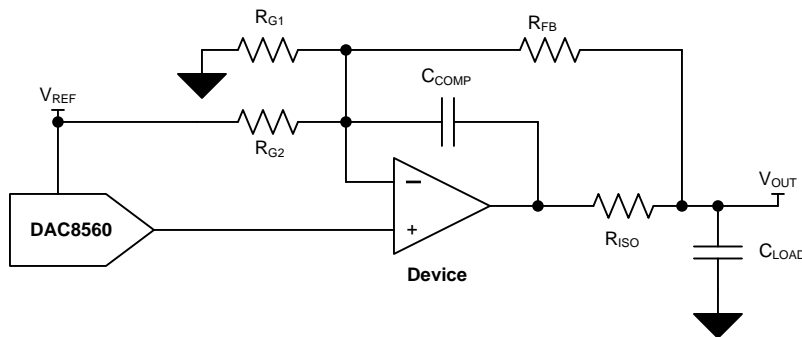
The OPAx180 family offers excellent DC precision and AC performance. These devices operate up to 36-V supply rails and offer rail-to-rail output, ultra-low offset voltage, offset voltage drift and 2-MHz bandwidth. These features make the OPAx180 a robust, high-performance amplifier for high-voltage industrial applications.

### 9.2 Typical Applications

These application examples highlight a few of the circuits where the OPAx180 family can be used.

#### 9.2.1 Bipolar $\pm 10$ -V Analog Output from a Unipolar Voltage Output DAC

This design is used for conditioning a unipolar digital-to-analog converter (DAC) into an accurate bipolar signal source using the OPAx180 family and three resistors. The circuit is designed with reactive load stability in mind, and is compensated to drive nearly any conventional capacitive load associated with long cable lengths.



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图 30. Circuit Schematic

#### 9.2.1.1 Design Requirements

The design requirements are as follows:

- DAC supply voltage: +5-V dc
- Amplifier supply voltage:  $\pm 15$ -V dc
- Input: 3-wire, 24-bit SPI
- Output:  $\pm 10$ -V dc

## Typical Applications (接下页)

### 9.2.1.2 Detailed Design Procedure

#### 9.2.1.2.1 Component Selection

**DAC:** For convenience, devices with an external reference option or devices with accessible internal references are desirable in this application because the reference creates an offset. The DAC selection in this design must primarily be based on DC error contributions typically described by offset error, gain error, and integral nonlinearity error. Occasionally, additional specifications are provided that summarize end-point errors of the DAC typically called zero-code and full-scale errors. For AC applications, slew rate and settling time may require additional consideration.

**Amplifier:** Amplifier input offset voltage ( $V_{IO}$ ) is a key consideration for this design.  $V_{IO}$  of an operational amplifier is a typical data sheet specification, but in-circuit performance is also affected by drift over temperature, the common-mode rejection ratio (CMRR), and power-supply rejection ratio (PSRR); thus consideration should be given to these parameters as well. For ac operation, additional considerations should be made concerning slew rate and settling time. Input bias current ( $I_B$ ) can also be a factor, but typically the resistor network is implemented with sufficiently small resistor values that the effects of input bias current are negligible.

**Passive:** Resistor matching for the op-amp resistor network is critical for the success of this design; components with tight tolerances must be selected. For this design, 0.1% resistor values are implemented, but this constraint may be adjusted based on application-specific design goals. Resistor matching contributes to offset error and gain error in this design; see [Bipolar  \$\pm 10V\$  Analog Output from a Unipolar Voltage Output DAC](#) for further details. The tolerance of the  $R_{ISO}$  and  $C_{COMP}$  stability components is not critical, and 1% components are acceptable.

#### 9.2.1.3 Application Curves

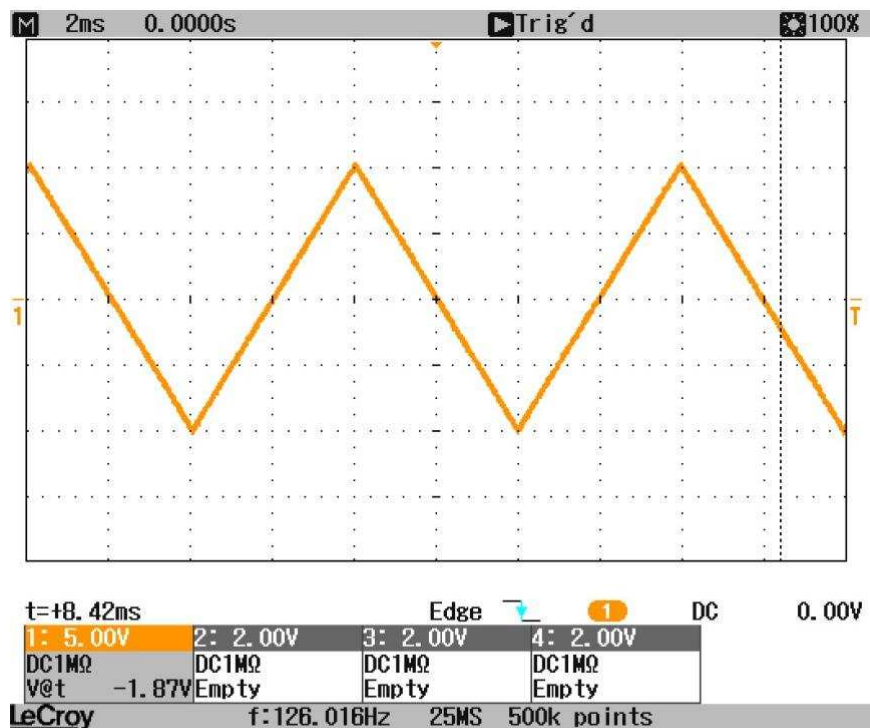
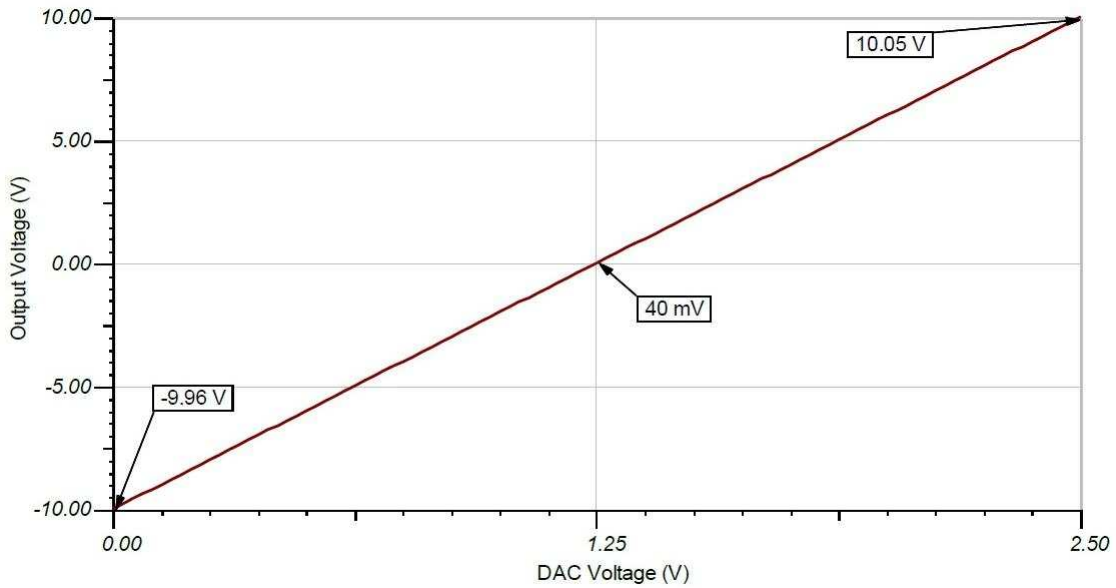


图 31. Full-Scale Output Waveform

**Typical Applications (接下页)**



**图 32. DC Transfer Characteristic**



For step-by-step design procedure, circuit schematics, bill of materials, PCB files, simulation results, and test results, refer to [TI Precision Design TIPD125, Bipolar ±10V Analog Output from a Unipolar Voltage Output DAC](#)

### 9.2.2 Discrete INA + Attenuation

The OPAx180 family can be used as a high-voltage, high-impedance front-end for a precision, discrete instrumentation amplifier with attenuation. The INA159 in [图 33](#) provides the attenuation that allows this circuit to simply interface with 3.3-V or 5-V analog-to-digital converters (ADCs).

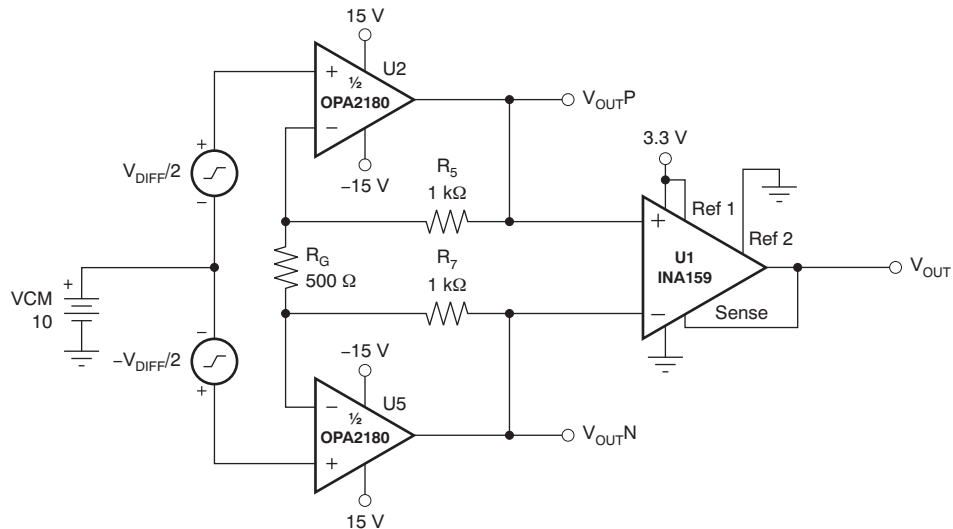
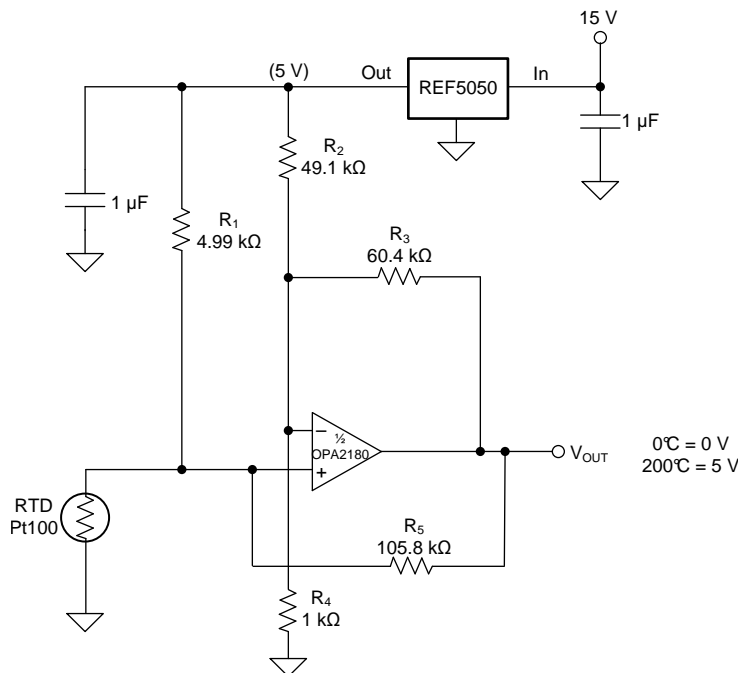


图 33. Discrete INA + Attenuation for ADC With a 3.3-V Supply

### 9.2.3 RTD Amplifier

The OPAx180 is excellent for use in analog linearization of resistance temperature detectors (RTDs). The circuit below ([图 34](#)) combines the precision of the OPAx180 amplifier and the precision reference of the REF5050 to linearize a Pt100 RTD.



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(1) R<sub>5</sub> provides positive-varying excitation to linearize output.

图 34. RTD Amplifier with Linearization



## 10 Power Supply Recommendations

The OPAx180 family is specified for operation from 4 V to 36 V ( $\pm 2$  V to  $\pm 18$  V); many specifications apply from  $-40^{\circ}\text{C}$  to  $+125^{\circ}\text{C}$ . Parameters that can exhibit significant variance with regard to operating voltage or temperature are presented in [Layout](#)

### CAUTION

Supply voltages larger than 40 V can permanently damage the device; see the [Absolute Maximum Ratings](#).

Place 0.1- $\mu\text{F}$  bypass capacitors close to the power-supply pins to reduce errors coupling in from noisy or high-impedance power supplies. For more detailed information on bypass capacitor placement, see [Layout](#).

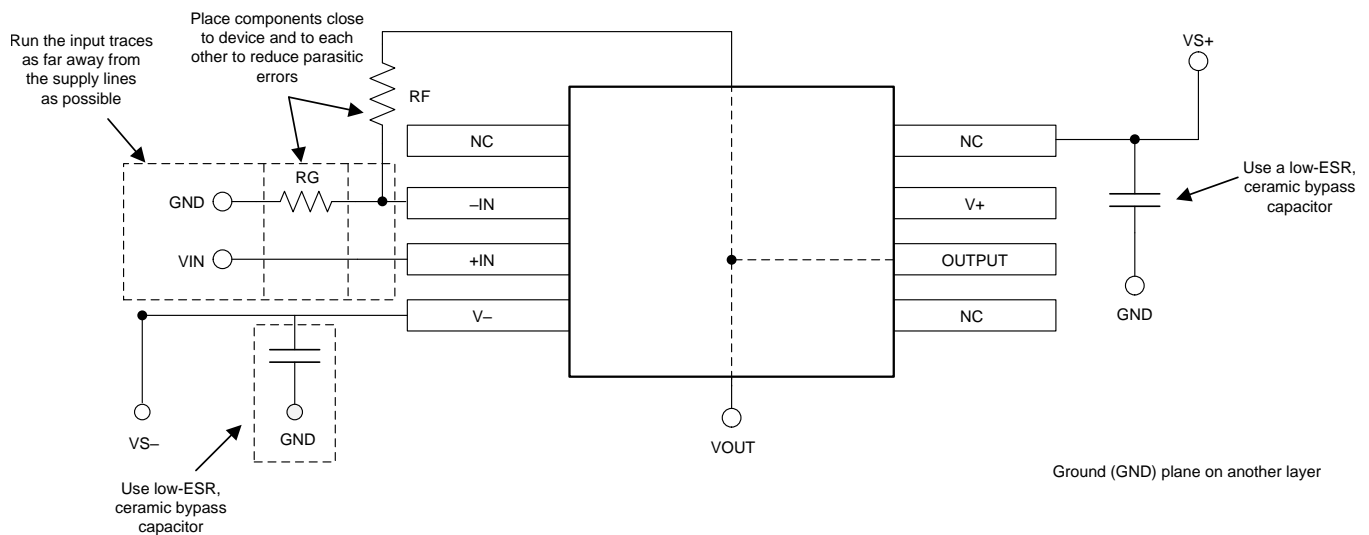
## 11 Layout

### 11.1 Layout Guidelines

For best operational performance of the device, use good printed circuit board (PCB) layout practices, including:

- Noise can propagate into analog circuitry through the power pins of the circuit as a whole and op amp itself. Bypass capacitors are used to reduce the coupled noise by providing low-impedance power sources local to the analog circuitry.
  - Connect low-ESR, 0.1- $\mu$ F ceramic bypass capacitors between each supply pin and ground, placed as close to the device as possible. A single bypass capacitor from V+ to ground is applicable for single-supply applications.
- Separate grounding for analog and digital portions of circuitry is one of the simplest and most-effective methods of noise suppression. One or more layers on multilayer PCBs are typically devoted to ground planes. A ground plane helps distribute heat and reduces EMI noise pickup. Take care to physically separate digital and analog grounds, paying attention to the flow of the ground current.
- In order to reduce parasitic coupling, run the input traces as far away from the supply or output traces as possible. If it is not possible to keep the input traces separate, it is much better to cross the sensitive trace perpendicular as opposed to in parallel with the noisy trace.
- Place the external components as close to the device as possible. As shown in [Figure 35](#), keeping RF and RG close to the inverting input minimizes parasitic capacitance.
- Keep the length of input traces as short as possible. Always remember that the input traces are the most sensitive part of the circuit.
- Consider a driven, low-impedance guard ring around the critical traces. A guard ring can significantly reduce leakage currents from nearby traces that are at different potentials.

### 11.2 Layout Example



**图 35. Operational Amplifier Board Layout for Noninverting Configuration**

## 12 器件和文档支持

### 12.1 相关链接

**表 3** 列出了快速访问链接。类别包括技术文档、支持与社区资源、工具和软件，以及申请样片或购买产品的快速链接。

**表 3. 相关链接**

器件	产品文件夹	立即订购	技术文档	工具与软件	支持和社区
OPA180	<a href="#">单击此处</a>	<a href="#">单击此处</a>	<a href="#">单击此处</a>	<a href="#">单击此处</a>	<a href="#">单击此处</a>
OPA2180	<a href="#">单击此处</a>	<a href="#">单击此处</a>	<a href="#">单击此处</a>	<a href="#">单击此处</a>	<a href="#">单击此处</a>
OPA4180	<a href="#">单击此处</a>	<a href="#">单击此处</a>	<a href="#">单击此处</a>	<a href="#">单击此处</a>	<a href="#">单击此处</a>

### 12.2 商标

All trademarks are the property of their respective owners.

### 12.3 静电放电警告



这些装置包含有限的内置 ESD 保护。存储或装卸时，应将导线一起截短或将装置放置于导电泡棉中，以防止 MOS 门极遭受静电损伤。

### 12.4 术语表

[SLYZ022](#) — TI 术语表。

这份术语表列出并解释术语、缩写和定义。

## 13 机械、封装和可订购信息

以下页面包含机械、封装和可订购信息。这些信息是指定器件的最新可用数据。数据如有变更，恕不另行通知，且不会对此文档进行修订。如需获取此产品说明书的浏览器版本，请查阅左侧的导航栏。

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
OPA180ID	ACTIVE	SOIC	D	8	75	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	OPA180	<a href="#">Samples</a>
OPA180IDBVR	ACTIVE	SOT-23	DBV	5	3000	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	SHJ	<a href="#">Samples</a>
OPA180IDBVT	ACTIVE	SOT-23	DBV	5	250	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	SHJ	<a href="#">Samples</a>
OPA180IDGKR	ACTIVE	VSSOP	DGK	8	2500	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	SHK	<a href="#">Samples</a>
OPA180IDGKT	ACTIVE	VSSOP	DGK	8	250	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	SHK	<a href="#">Samples</a>
OPA180IDR	ACTIVE	SOIC	D	8	2500	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	OPA180	<a href="#">Samples</a>
OPA2180ID	ACTIVE	SOIC	D	8	75	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	2180	<a href="#">Samples</a>
OPA2180IDGK	ACTIVE	VSSOP	DGK	8	80	RoHS & Green	NIPDAUAG	Level-2-260C-1 YEAR	-40 to 125	2180	<a href="#">Samples</a>
OPA2180IDGKR	ACTIVE	VSSOP	DGK	8	2500	RoHS & Green	NIPDAU   SN   NIPDAUAG	Level-2-260C-1 YEAR	-40 to 125	2180	<a href="#">Samples</a>
OPA2180IDR	ACTIVE	SOIC	D	8	2500	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	2180	<a href="#">Samples</a>
OPA4180ID	ACTIVE	SOIC	D	14	50	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	OPA4180	<a href="#">Samples</a>
OPA4180IDR	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	OPA4180	<a href="#">Samples</a>
OPA4180IPW	ACTIVE	TSSOP	PW	14	90	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	OPA4180	<a href="#">Samples</a>
OPA4180IPWR	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	OPA4180	<a href="#">Samples</a>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSELETE:** TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of  $\leq 1000$ ppm threshold. Antimony trioxide based flame retardants must also meet the  $\leq 1000$ ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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**OTHER QUALIFIED VERSIONS OF OPA180, OPA2180 :**

- Automotive : [OPA180-Q1](#), [OPA2180-Q1](#)

NOTE: Qualified Version Definitions:

- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects

**TAPE AND REEL INFORMATION**

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
OPA180IDBVR	SOT-23	DBV	5	3000	178.0	9.0	3.3	3.2	1.4	4.0	8.0	Q3
OPA180IDBVR	SOT-23	DBV	5	3000	180.0	8.4	3.23	3.17	1.37	4.0	8.0	Q3
OPA180IDBVT	SOT-23	DBV	5	250	180.0	8.4	3.23	3.17	1.37	4.0	8.0	Q3
OPA180IDGKR	VSSOP	DGK	8	2500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
OPA180IDGKT	VSSOP	DGK	8	250	177.8	12.4	5.3	3.4	1.4	8.0	12.0	Q1
OPA180IDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
OPA2180IDGKR	VSSOP	DGK	8	2500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
OPA2180IDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
OPA4180IDR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
OPA4180IPWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
OPA180IDBVR	SOT-23	DBV	5	3000	190.0	190.0	30.0
OPA180IDBVR	SOT-23	DBV	5	3000	223.0	270.0	35.0
OPA180IDBVT	SOT-23	DBV	5	250	223.0	270.0	35.0
OPA180IDGKR	VSSOP	DGK	8	2500	346.0	346.0	29.0
OPA180IDGKT	VSSOP	DGK	8	250	223.0	270.0	35.0
OPA180IDR	SOIC	D	8	2500	356.0	356.0	35.0
OPA2180IDGKR	VSSOP	DGK	8	2500	353.0	353.0	32.0
OPA2180IDR	SOIC	D	8	2500	356.0	356.0	35.0
OPA4180IDR	SOIC	D	14	2500	356.0	356.0	35.0
OPA4180IPWR	TSSOP	PW	14	2000	356.0	356.0	35.0

**TUBE**


\*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
OPA180ID	D	SOIC	8	75	506.6	8	3940	4.32
OPA2180ID	D	SOIC	8	75	506.6	8	3940	4.32
OPA2180IDGK	DGK	VSSOP	8	80	330	6.55	500	2.88
OPA4180ID	D	SOIC	14	50	506.6	8	3940	4.32
OPA4180IPW	PW	TSSOP	14	90	508	8.5	3250	2.8





D0008A

# PACKAGE OUTLINE

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



4214825/C 02/2019

NOTES:

- Linear dimensions are in inches [millimeters]. Dimensions in parenthesis are for reference only. Controlling dimensions are in inches. Dimensioning and tolerancing per ASME Y14.5M.
- This drawing is subject to change without notice.
- This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed  $.006$  [0.15] per side.
- This dimension does not include interlead flash.
- Reference JEDEC registration MS-012, variation AA.

# EXAMPLE BOARD LAYOUT

D0008A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE:8X



SOLDER MASK DETAILS

4214825/C 02/2019

NOTES: (continued)

- 6. Publication IPC-7351 may have alternate designs.
- 7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

D0008A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



SOLDER PASTE EXAMPLE  
BASED ON .005 INCH [0.125 MM] THICK STENCIL  
SCALE:8X

4214825/C 02/2019

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

PW0014A



**PACKAGE OUTLINE**  
**TSSOP - 1.2 mm max height**

SMALL OUTLINE PACKAGE



4220202/B 12/2023

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.

# EXAMPLE BOARD LAYOUT

PW0014A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE: 10X



4220202/B 12/2023

NOTES: (continued)

- 6. Publication IPC-7351 may have alternate designs.
- 7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

PW0014A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE: 10X

4220202/B 12/2023

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

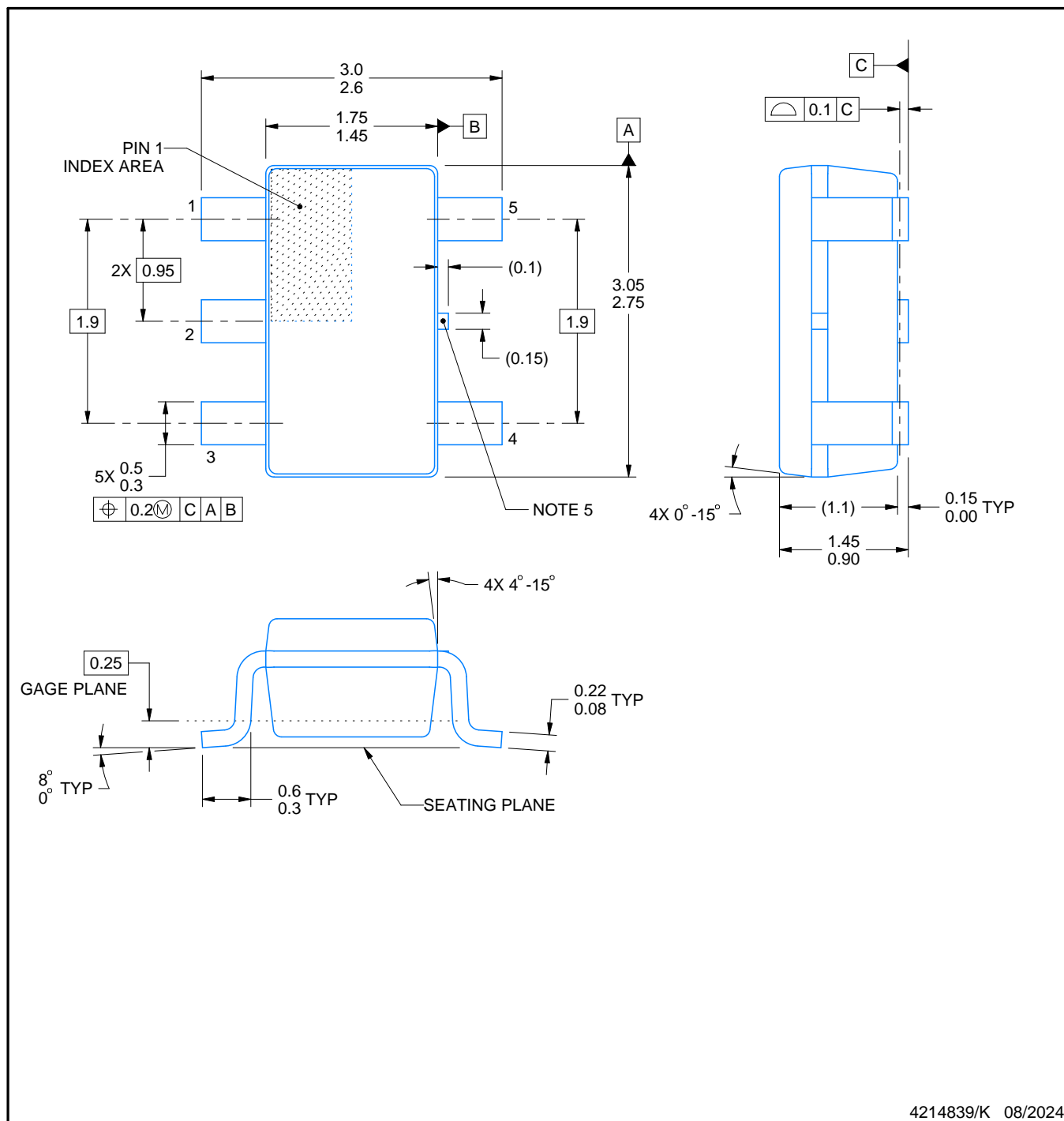
## DBV0005A



## PACKAGE OUTLINE

SOT-23 - 1.45 mm max height

SMALL OUTLINE TRANSISTOR



4214839/K 08/2024

## NOTES:

- All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- This drawing is subject to change without notice.
- Reference JEDEC MO-178.
- Body dimensions do not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.25 mm per side.
- Support pin may differ or may not be present.

# EXAMPLE BOARD LAYOUT

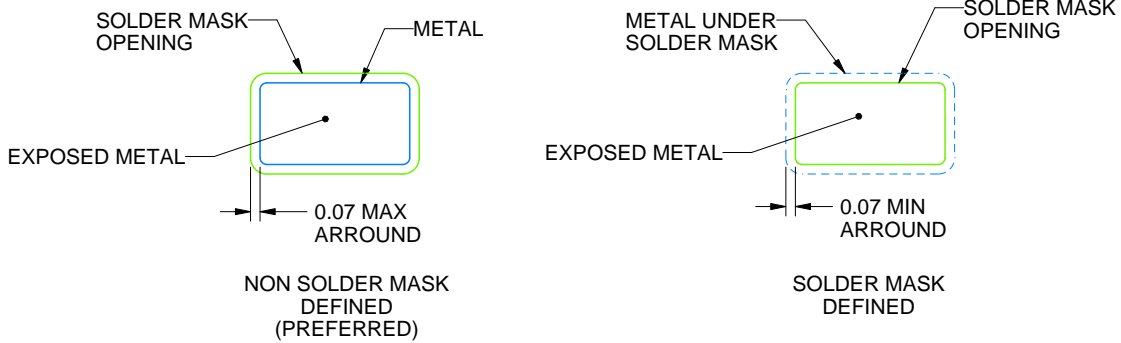
DBV0005A

SOT-23 - 1.45 mm max height

SMALL OUTLINE TRANSISTOR



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE:15X



SOLDER MASK DETAILS

4214839/K 08/2024

NOTES: (continued)

- 6. Publication IPC-7351 may have alternate designs.
- 7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



# EXAMPLE STENCIL DESIGN

DBV0005A

SOT-23 - 1.45 mm max height

SMALL OUTLINE TRANSISTOR



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE:15X

4214839/K 08/2024

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

# DGK0008A



# PACKAGE OUTLINE

VSSOP - 1.1 mm max height

SMALL OUTLINE PACKAGE



4214862/A 04/2023

**NOTES:**

PowerPAD is a trademark of Texas Instruments.

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-187.

# EXAMPLE BOARD LAYOUT

DGK0008A

™ VSSOP - 1.1 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE: 15X



SOLDER MASK DETAILS

4214862/A 04/2023

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.
8. Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.
9. Size of metal pad may vary due to creepage requirement.

# EXAMPLE STENCIL DESIGN

DGK0008A

<sup>TM</sup> VSSOP - 1.1 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE  
SCALE: 15X

4214862/A 04/2023

NOTES: (continued)

11. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
12. Board assembly site may have different recommendations for stencil design.



# D0014A

# PACKAGE OUTLINE

## SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



4220718/A 09/2016

### NOTES:

1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm, per side.
5. Reference JEDEC registration MS-012, variation AB.

# EXAMPLE BOARD LAYOUT

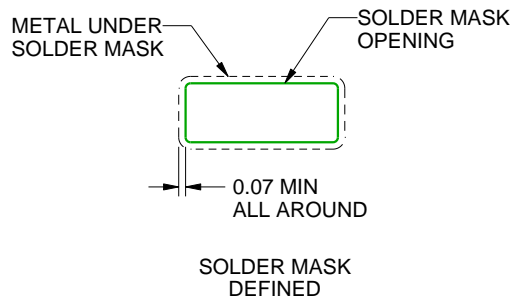
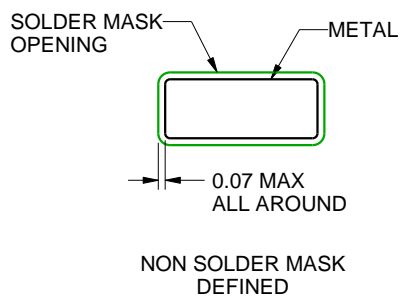
D0014A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



LAND PATTERN EXAMPLE  
SCALE:8X



SOLDER MASK DETAILS

4220718/A 09/2016

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

D0014A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE:8X

4220718/A 09/2016

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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